Listing of the Claims:

1-20. (Cancelled)

21. (Previously Presented) An electronic device comprising:

a display layer; and

a cover layer coupled to the display layer, formed from a glass material, and comprising:

a foldable first portion defining a relief feature and a first thickness at the relief feature, the foldable first portion comprising a first exterior compressive stress region having a first depth from an exterior surface of the cover layer;

a second portion defining a second thickness, greater than the first thickness, and comprising a second exterior compressive stress region having a second depth, greater than the first depth, from the exterior surface of the cover layer; and

a third portion, the foldable first portion positioned between the second and the third portions, the third portion having a third thickness, greater than the first thickness and comprising a third exterior compressive stress region having a third depth, greater than the first depth, from the exterior surface of the cover layer, wherein:

the display layer and the cover layer are configured to be moved between a folded configuration and an unfolded configuration by bending the foldable first portion.

22. (Previously Presented) The electronic device of claim 21, wherein:

the foldable first portion of the cover layer defines a bend that spans a width of the cover layer in the folded configuration; and

an interior surface of the cover layer defines an outside of the bend in the folded configuration.

23. (Previously Presented) The electronic device of claim 22, wherein:

the foldable first portion further comprises a first interior compressive stress region having a fourth depth from the interior surface of the cover layer;

the second portion further comprises a second interior compressive stress region having a fifth depth, greater than the fourth depth, from the interior surface of the cover layer; and

the third portion further comprises a third interior compressive stress region having a sixth depth, greater than the fourth depth, from the interior surface of the cover layer.

24. (Previously Presented) The electronic device of claim 23, wherein the relief feature is a recess defined by the interior surface of the cover layer.

25. (Previously Presented) The electronic device of claim 23, further comprising a polymer filler material disposed in the relief feature and optically matched to the cover layer.

26. (Previously Presented) The electronic device of claim 23, wherein:

the glass material is an aluminosilicate glass material;

each of the second exterior compressive stress region, the second interior compressive stress region, the third exterior compressive stress region, and the third interior compressive stress region comprises:

first ions introduced by a first ion exchange operation; and

second ions introduced by a second ion exchange operation; and

each of the first exterior compressive stress region and the first interior compressive stress region comprises the second ions introduced by the second ion exchange operation.

27. (Previously Presented) The electronic device of claim 26, wherein the

the glass material comprises lithium ions;

the first ions are sodium ions; and

the second ions are potassium ions.

28. (Previously Presented) An electronic device comprising:

a display layer; and

a cover layer formed from a glass material and coupled to the display layer, the cover layer comprising:

a first portion defining a bend in in a folded configuration of the cover layer and the display layer, the first portion further defining a first thickness and comprising a first exterior compressive stress region having a first depth;

a second portion defining a second thickness, greater than the first thickness, and comprising a second exterior compressive stress region having a second depth, greater than the first depth; and

a third portion, each of the third portion and the second portion partly surrounding the first portion, the third portion defining a third thickness, greater than the first thickness, and

the third portion comprising a third exterior compressive stress region having a third depth, greater than the first depth.

29. (Previously Presented) The electronic device of claim 28, wherein:

the first portion of the cover layer further defines a recessed portion of an interior surface of the cover layer; and

the first thickness is defined between an exterior surface and the recessed portion of the interior surface.

30. (Previously Presented) The electronic device of claim 29, wherein the recessed portion of the interior surface at least partially defines an exterior surface of the bend in the folded configuration.

31. (Previously Presented) The electronic device of claim 29, wherein the recessed portion of the interior surface defines a recess depth that is in a range from 20% to 70% of each of the second thickness and the third thickness.

32. (Previously Presented) The electronic device of claim 29, wherein:

the first portion of the cover layer further comprises a first interior compressive stress region having a fourth depth;

the second portion of the cover layer further comprises a second interior compressive stress region having a fifth depth, greater than the fourth depth; and

the third portion of the cover layer further comprises a third interior compressive stress region having a sixth depth, greater than the fourth depth.

33. (Previously Presented) The electronic device of claim 32, wherein:

the second depth of the second exterior compressive stress region and the third depth of the third exterior compressive stress region are a same depth; and

the fifth depth of the second exterior compressive stress region and the sixth depth of the third interior compressive stress region are a same depth.

34. (Previously Presented) The electronic device of claim 33, wherein the first depth of the first exterior compressive stress region and the fourth depth of the first interior compressive stress region are a same depth.

35. (Previously Presented) A system comprising:

a cover layer formed from a glass material and comprising:

a first portion defining a bend in a folded configuration of the cover layer, the first portion having a first thickness and comprising:

a first exterior compressive stress region having a first depth from an exterior surface of the cover layer; and

a first interior compressive stress region having a fourth depth from an interior surface of the cover layer;

a second portion having a second thickness, greater than the first thickness, and comprising:

a second exterior compressive stress region having a second depth, greater than the first depth, from the exterior surface; and

a second interior compressive stress region having a fifth depth, greater than the fourth depth from the interior surface; and

a third portion, the first portion positioned between the first and the second portions, the third portion having a third thickness, greater than the first thickness, and comprising:

a third exterior compressive stress region having a third depth, greater than the first depth, from the exterior surface; and

a third interior compressive stress region having a sixth depth, greater than the fourth depth, from the interior surface.

36. (Previously Presented) The system of claim 35, wherein:

the exterior surface of the cover layer defines an interior surface of the bend; and

the interior surface of the cover layer defines a recessed region.

37. (Previously Presented) The system of claim 36, wherein:

the cover layer defines a width and a length that is greater than the width; and

each of the first portion, the second portion, and the third portion spans the width of the cover layer.

38. (Previously Presented) The system of claim 36, wherein each of the first thickness, the second thickness and the third thickness is in a range from 25 micrometers to 400 micrometers.

39. (Previously Presented) The system of claim 38, wherein the second thickness and the third thickness are a same thickness.

40. (Previously Presented) The system of claim 35, wherein:

the exterior surface of the cover layer defines an interior surface of the bend;

the exterior surface of the cover layer defines a recessed region; and

the system further comprises a flexible coating disposed over the recessed region of the exterior surface of the cover layer.